IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes

July 16-18, 2019, Bochum, Germany

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Full Conference Details at
http://imws-ieee.org

CALL FOR PAPERS

IMWS-AMP 2019 conference represents a unique and unprecedented opportunity to bring together researchers and practitioners of different background (materials scientists, chemical experts, physicists, microwave engineers and process technologists), to share the most recent advances in new materials and manufacturing processes, which represent the key for the development of future RF, microwave, mm-wave and THz devices, circuits and systems. IMWS-AMP 2019 is **organized by the IEEE Microwave Theory and Techniques Society (MTT-S) with the technical co-sponsorship of the European Microwave Association (EuMA)**. The conference will feature an exciting technical program and invited talks by worldwide recognized experts in materials and manufacturing processes.

CONFERENCE TOPICS

Perspective authors are cordially invited to submit papers in all areas of novel material, advanced manufacturing and processing, and integration techniques for microwave to terahertz circuits and systems, including but not limited to:

- **RF, microwave and THz components and circuits based on new materials**
- **Additive manufacturing & 3D-printing**
- **Wearable components and antennas**
- **Organic RF electronics and devices**
- **Components based on inkjet printing**
- **Smart and functional materials**
- **Sensor technologies**
- **Artificial and engineered materials**
- **Advanced manufacturing process**
- **Microwave devices based on semiconductor materials**
- **Nanomaterials (e.g., graphene, CNT)**
- **High-speed memory materials**
- **Bio-materials**
- **Multiphysics modeling**
- **Material characterization**
- **Integration and interconnect technologies**

Submitted papers should be **three pages** in length. Authors must adhere to the format of the IEEE conference paper template.

Submission deadline:	**April 15, 2019**
Notification of acceptance:	May 17, 2019
Final paper submission:	May 31, 2019
Conference date:	July 16-18, 2019

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EuMA European Microwave Association







